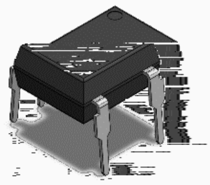
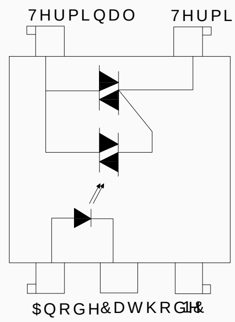
59 { /wLt¢LhbY

The products are 5-pin solid-state relay opto-couplers. The device combines an AlGaAs infrared emitting diode as the emitter which is optically coupled to a monolithic silicon random-phase photo triac to drive a power triac in a plastic DIP5 package with different lead forming options. The products are widely used in solenoid/valve controls, light controls, motor controls, temperature controls, static AC power switches, solid state relays, interfacing microprocessors to 265 V_{AC} peripherals.





a ! Lb C9 ! ¢ ¦ w9 { Y

- High isolation 5000 Vrms
- DC input with triac output
- Operating temperature range -40 ÁC to 110 ÁC
- REACH & RoHS compliance
- HBM: H3B ; MM: M4 ; CDM: C3
- CQC approved
- VDE approved
- UL approved

! . { h [¦ ¢ 9 a ! · La ¦ a w (! a . L 9 b ¢ Temperature = 25 ÁC)

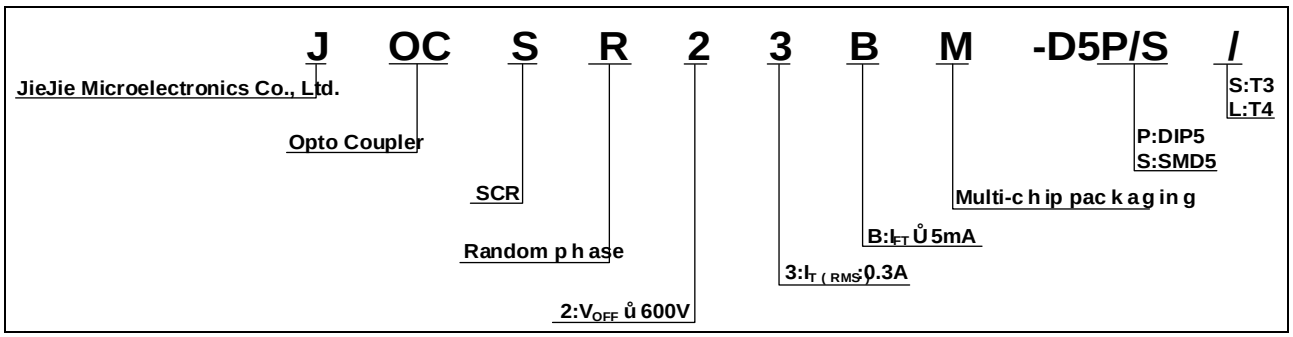
Parameter		Symbol	Value	Unit
Input	Forward Current	I_F	50	mA
	Peak Forward Current	I_{FP}	1 ŵ	A
	Reverse Voltage	V_R	6	V
	Power Dissipation	P_D	75	mW
Output	Repetitive peak off-state voltage	V_{DRM}	600	V
	Repetitive peak reverse voltage	V_{RRM}	600	V
	Critical rate of rise of on-state current	dI/dt	100	A/ε s
	On-state RMS Current (ȁ 0 80-	,7 506		
	1RQ UHSHWLWLYH SHDN RQ VWDWH FXUUHQW IXOOVF\FOH W 760			
	MXQFWLRQ WR FDVH $& 5WK MF			:

Isolation Voltage	V_{iso}	5000 Ŷ	Vrms
Operating Temperature	T_{opr}	-40 ~ 110	Ņ
Junction Temperature	T_j	125	Ņ
Storage Temperature	T_{stg}	-40 ~ 125	Ņ
Soldering Temperature	T_{sol}	260	Ņ
Peak pulse voltage (T=25 Ņ ; non-repetitive,off-state)	V_{pp}	3	kV

bh¢9млл>ă ǈMdz ñĦ ŜŜ ǉdzŜ ƴŎè
bh¢9ɨ/ Ŧ 2ǋ мΎ ƛ ƴdzű Ŝ Σ wΦlΦ Ɠ пл Ч с л

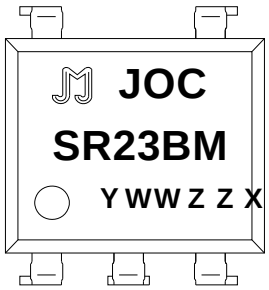
9[9/¢wL/! [/I! w ! / ¢ 9 w L { ¢ L / { (Temperature = 25 ÁC)

h w59wLbD LbC h wa ! ¢L h b



t l· Ŏ ļ ƛ ƴ Ǝ vdz l· ƴ ű ƛ ű è	
h LJ ű ƛ ƨ ƴ	vdz l· ƴ ű ƛ ű è
5Lt	c л ¦ ƴ ƛ ű ă к ¢ dz ō Ŝ
{ a5	м н л л ¦ ƴ ƛ ű ă к w Ŝ Ŝ f

a ! w Y LbD



YWWZZX

LOT NO.

/Ќ l· NJ l· Ŏ ű Ŝ NJ ƛ ă ű ƛ Ŏ ă /dzNJ Ø Ŝ ă

FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

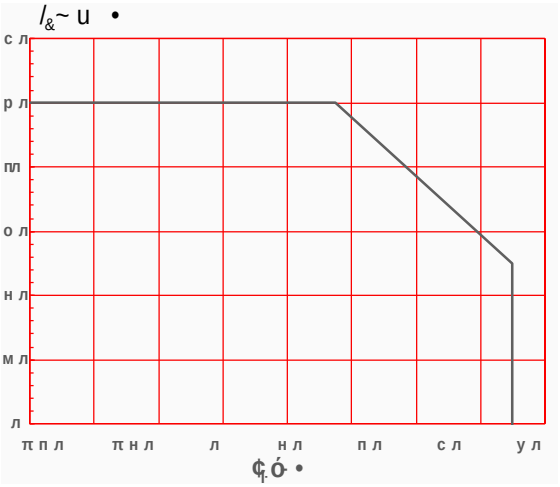


FIG.2: On-state Terminal Current vs. Ambient Temperature

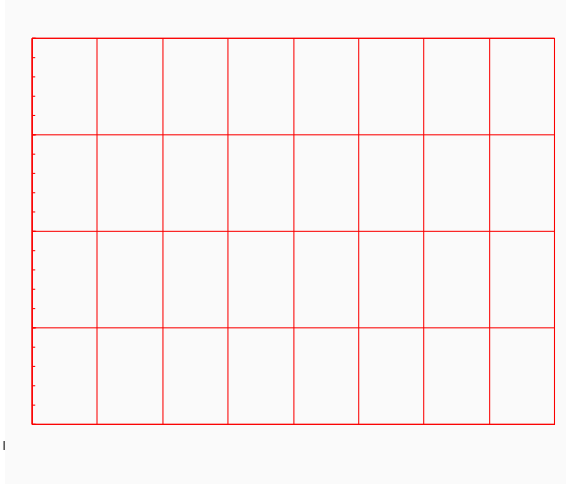


FIG.7: On-state c h aracteristics

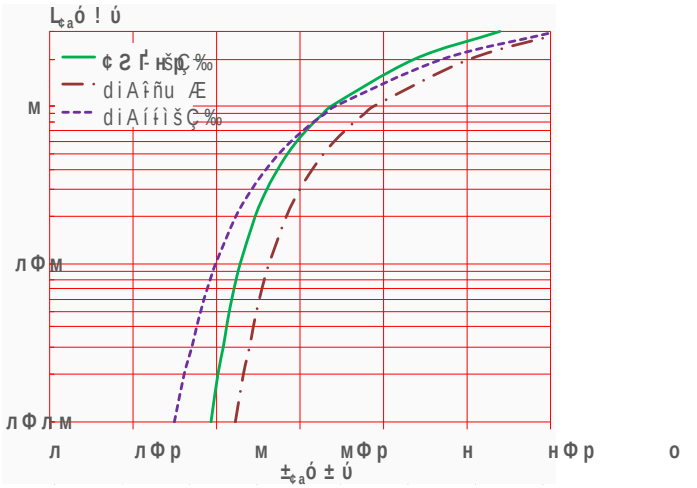


FIG.8: Normali z ed H oldin g Current vs. Ambient Temperature

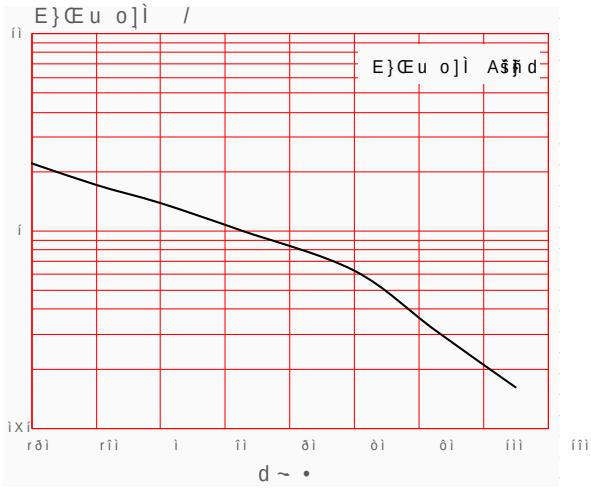
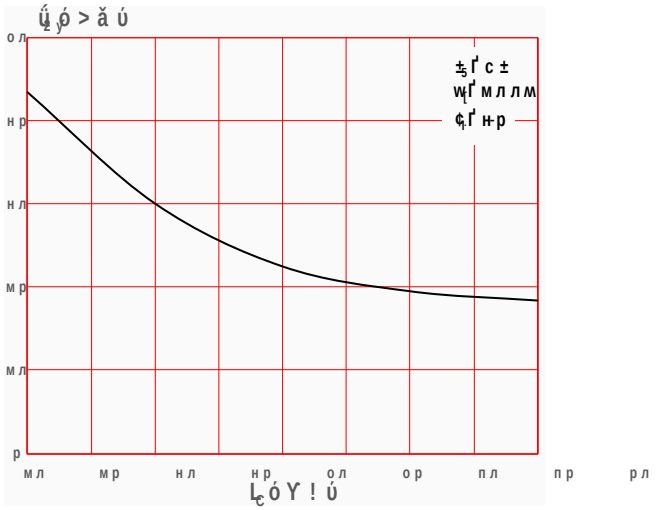
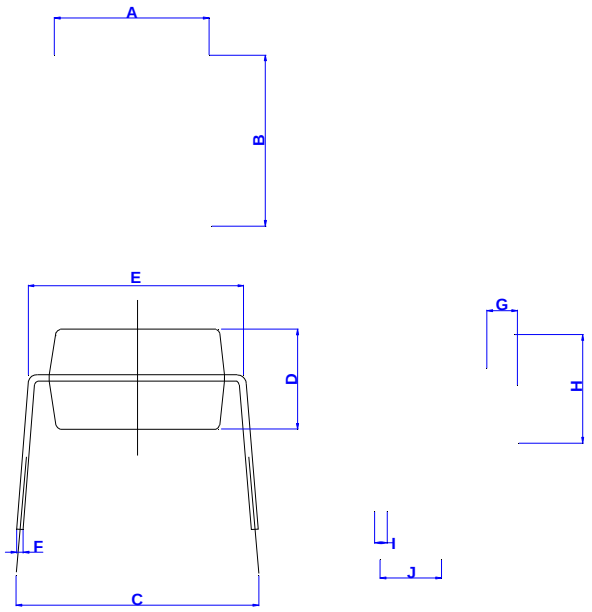


FIG.9: Turn On Time vs. For w ard Current



t l· Ŏ ļ l· Ǝ Ŝ 5 ƛ Ƴ Ŝ ƴ ă ƛ ƨ ƴ ó ¦ ƴ ƛ ű Ƴ Ƴ Ƴ ú

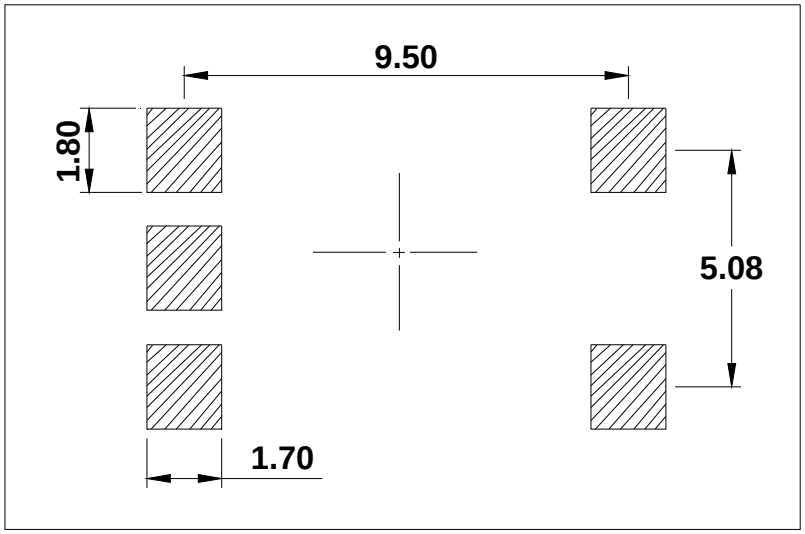
Standard DIP Type:



Dimensions	
Millimeters	Incio Â

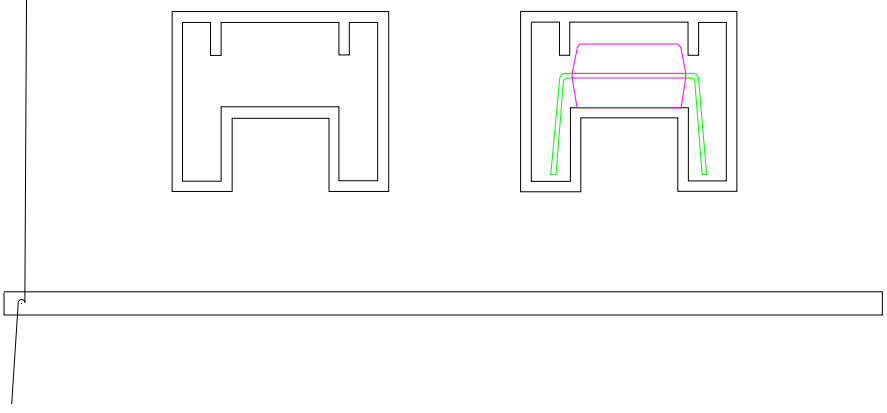
w9/haa9b595 { h [59w a ! { Y ó5ƛYŜyăƛ2yăƛyYŜkzýf Ŝăă

Option SMD

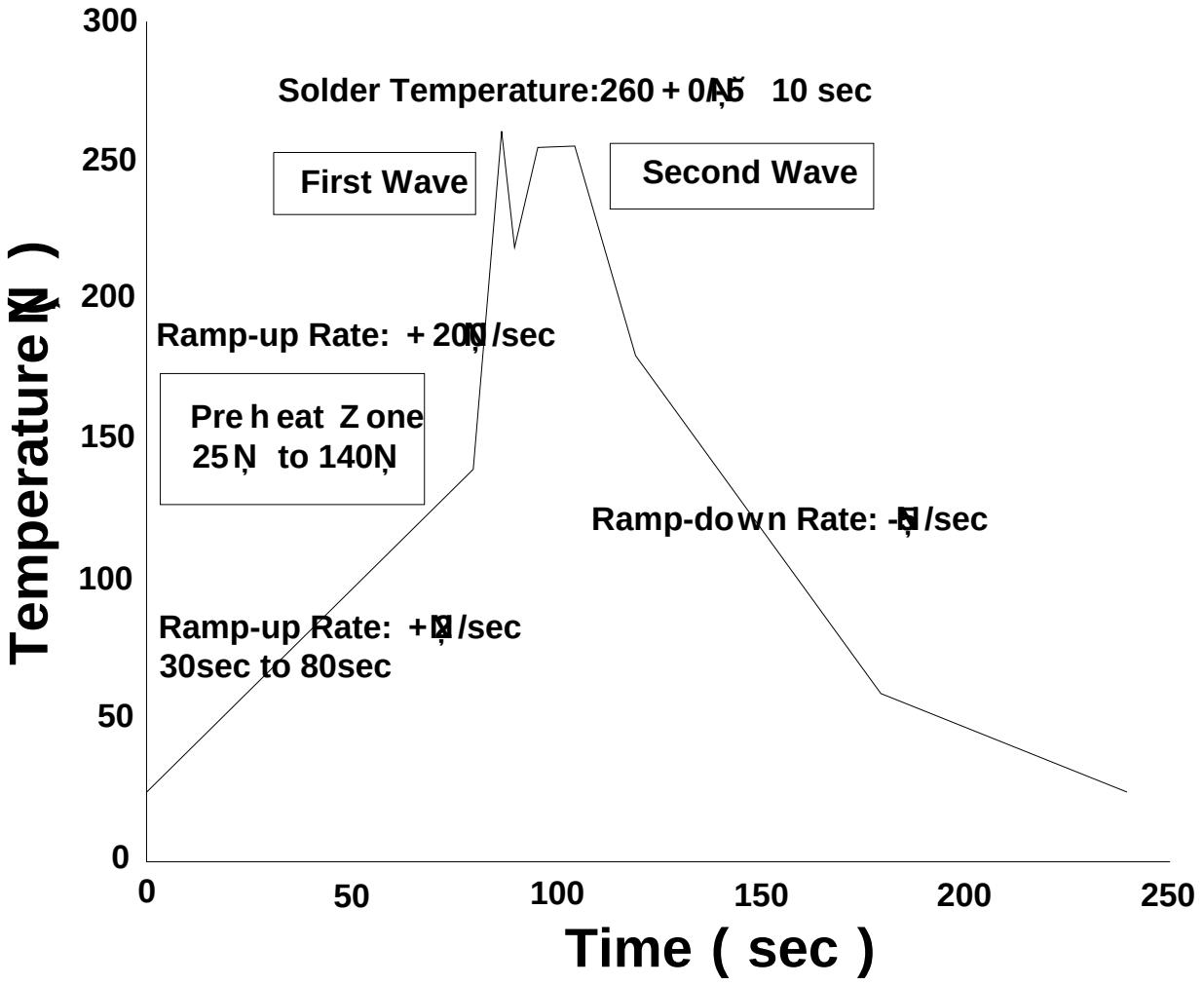


¢¦.9 {t9/LCL/ ! ¢Lhb{ ó5ƛYŜyăƛ2yăƛyYYdzyfŜăă2űKŜ

Standard DIP



² ! ±9 { h [59wLbD



I ! b5 { h [59wLbD . { h [59wLbD Lw h b	
Soldering Temperature	360 ¤ 5
Soldering Time	3s max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body